

**Features:**

- Isolated mounting base 2500V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving

**Typical Applications**

- Inverter
- Inductive heating
- Chopper

V <sub>RSM</sub>	V <sub>RRM</sub>	品名
900V	800V	Mx400DF80
1100V	1000V	Mx400DF100
1300V	1200V	Mx400DF120
1500V	1400V	Mx400DF140
1700V	1600V	Mx400DF160

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T <sub>j</sub> (°C)	VALUE			UNIT
				Min.	Typ.	Max.	
I <sub>F(AV)</sub>	Mean forward current	180° half sine wave 50Hz Single side cooled, T <sub>c</sub> =60°C	150			400	A
I <sub>F(RMS)</sub>	RMS forward current					628	A
I <sub>RRM</sub>	Repetitive peak current	at V <sub>RRM</sub>	150			90	mA
I <sub>FSM</sub>	Surge forward current	10ms half sine wave V <sub>R</sub> =0.6V <sub>RRM</sub>	150			9.5	kA
I <sup>2</sup> t	I <sup>2</sup> t for fusing coordination					451	A <sup>2</sup> s*10 <sup>3</sup>
V <sub>FO</sub>	Threshold voltage		150			1.10	V
r <sub>F</sub>	Forward slope resistance					0.27	mΩ
V <sub>FM</sub>	Peak forward voltage	I <sub>FM</sub> =1200A	25			1.60	V
t <sub>rr</sub>	Reverse recovery time	I <sub>FM</sub> =300A, t <sub>p</sub> =2000μs, -di/dt=20A/μs, V <sub>R</sub> =50V	150			4.0	μs
R <sub>th(j-c)</sub>	Thermal resistance Junction to case	D.C. Single side cooled per chip				0.090	°C /W
R <sub>th(c-h)</sub>	Thermal resistance case to heatsink	D.C. Single side cooled per chip				0.020	°C /W
V <sub>iso</sub>	Isolation voltage	50Hz, R.M.S, t=1min, I <sub>iso</sub> :1mA(MAX)		2500			V
F <sub>m</sub>	Terminal connection torque(M14)				14.0		N·m
	Mounting torque(M12)				12.0		N·m
T <sub>vj</sub>	Junction temperature			-40		140	°C
T <sub>stg</sub>	Stored temperature			-40		125	°C
W <sub>t</sub>	Weight				3240		g
Outline	M07						

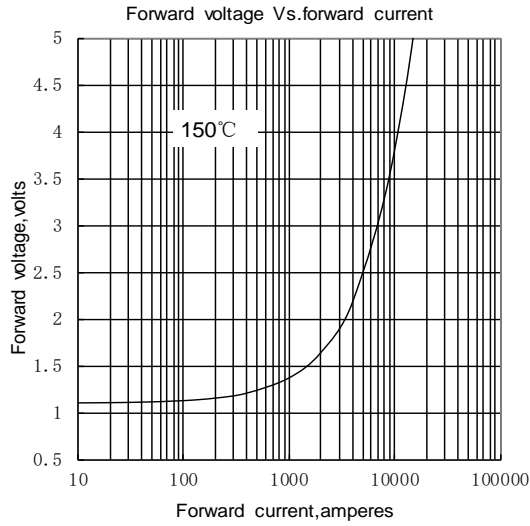


Fig.1

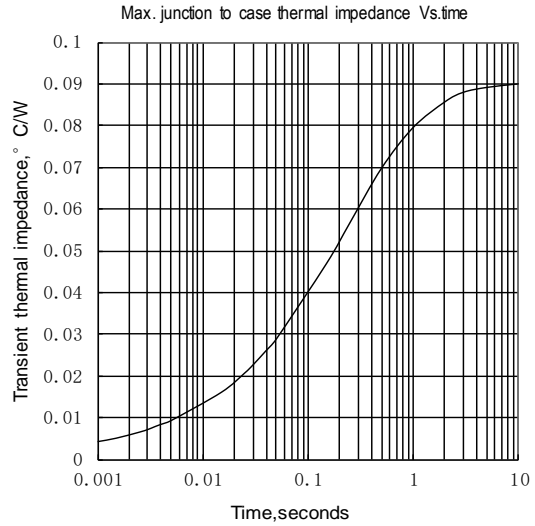


Fig.2

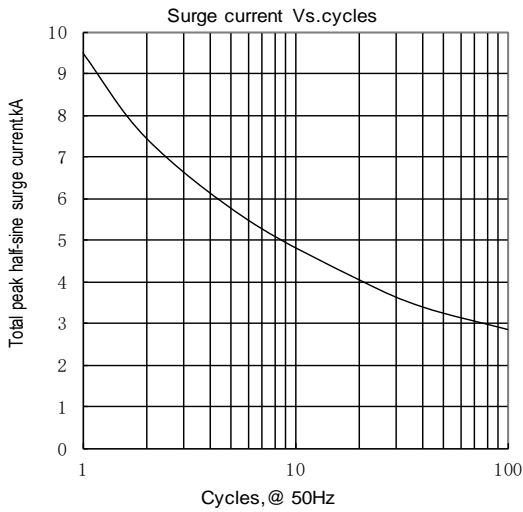
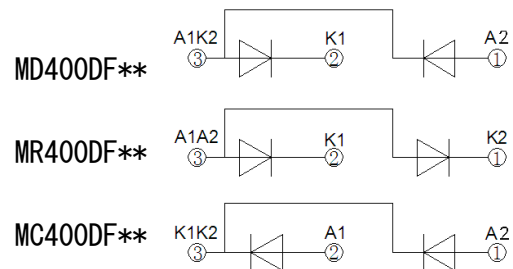
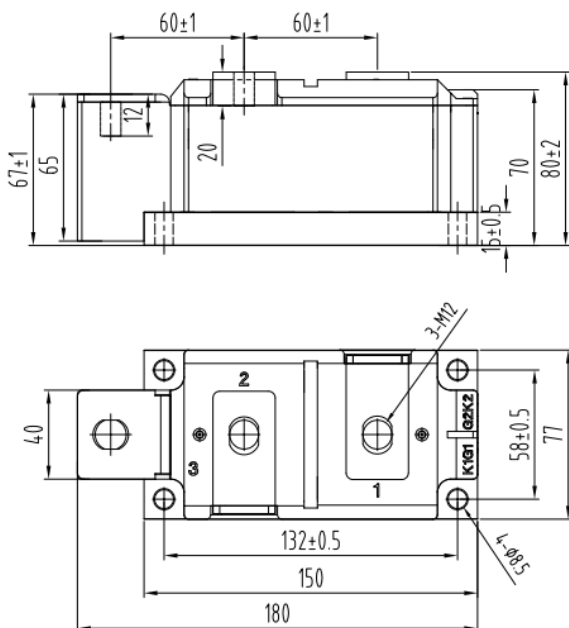


Fig.3



Unmarked dimensional tolerance : ±0.5mm

Nips reserves the right to change specifications without notice.